

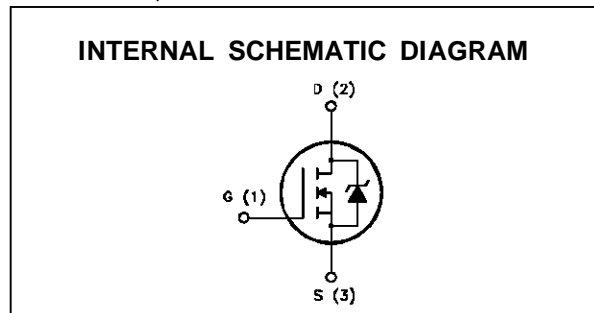
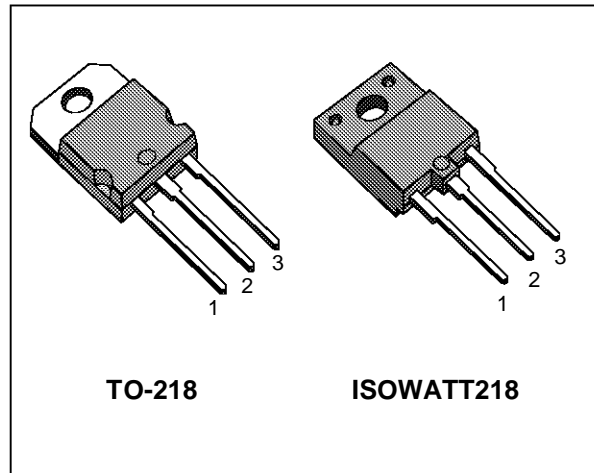
N - CHANNEL ENHANCEMENT MODE POWER MOS TRANSISTOR

| TYPE | V _{DSS} | R _{DS(on)} | I _D |
|------------|------------------|---------------------|----------------|
| STH6N100 | 1000 V | < 2 Ω | 6 A |
| STH6N100FI | 1000 V | < 2 Ω | 3.7 A |

- TYPICAL R_{DS(on)} = 1.75 Ω
- AVALANCHE RUGGED TECHNOLOGY
- 100% AVALANCHE TESTED
- REPETITIVE AVALANCHE DATA AT 100°C
- LOW INPUT CAPACITANCE
- LOW GATE CHARGE
- APPLICATION ORIENTED CHARACTERIZATION

APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITCH MODE POWER SUPPLIES (SMPS)
- CONSUMER AND INDUSTRIAL LIGHTING
- DC-AC INVERTERS FOR WELDING EQUIPMENT AND UNINTERRUPTIBLE POWER SUPPLY (UPS)



ABSOLUTE MAXIMUM RATINGS

| Symbol | Parameter | Value | | Unit |
|---------------------|-------------------------------------------------------|------------|----------|------|
| | | STH6N100 | STH6N100 | |
| V _{DS} | Drain-source Voltage (V _{GS} = 0) | 1000 | | V |
| V _{DGR} | Drain- gate Voltage (R _{GS} = 20 kΩ) | 1000 | | V |
| V _{GS} | Gate-source Voltage | ± 20 | | V |
| I _D | Drain Current (continuous) at T _c = 25 °C | 6 | 3.7 | A |
| I _D | Drain Current (continuous) at T _c = 100 °C | 3.7 | 2.3 | A |
| I _{DM} (●) | Drain Current (pulsed) | 24 | 24 | A |
| P _{tot} | Total Dissipation at T _c = 25 °C | 180 | 70 | W |
| | Derating Factor | 1.44 | 0.56 | W/°C |
| V _{ISO} | Insulation Withstand Voltage (DC) | — | 4000 | V |
| T _{stg} | Storage Temperature | -65 to 150 | | °C |
| T _j | Max. Operating Junction Temperature | 150 | | °C |

(●) Pulse width limited by safe operating area

THERMAL DATA

| | | | TO-218 | ISOWATT218 | |
|-----------------------|------------------------------------------------|-----|---------------|-------------------|------|
| R _{thj-case} | Thermal Resistance Junction-case | Max | 0.69 | 1.78 | °C/W |
| R _{thj-amb} | Thermal Resistance Junction-ambient | Max | 30 | | °C/W |
| R _{thc-sink} | Thermal Resistance Case-sink | Typ | 0.1 | | °C/W |
| T _l | Maximum Lead Temperature For Soldering Purpose | | 300 | | °C |

AVALANCHE CHARACTERISTICS

| Symbol | Parameter | Max Value | Unit |
|-----------------|------------------------------------------------------------------------------------------------------------------------------|-----------|------|
| I _{AR} | Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T _j max, δ < 1%) | 6 | A |
| E _{AS} | Single Pulse Avalanche Energy (starting T _j = 25 °C, I _D = I _{AR} , V _{DD} = 25 V) | 850 | mJ |
| E _{AR} | Repetitive Avalanche Energy (pulse width limited by T _j max, δ < 1%) | 16 | mJ |
| I _{AR} | Avalanche Current, Repetitive or Not-Repetitive (T _c = 100 °C, pulse width limited by T _j max, δ < 1%) | 3.7 | A |

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|----------------------|-------------------------------------------------------|--------------------------------------------------------------------------------------------|------|------|-----------|----------|
| V _{(BR)DSS} | Drain-source Breakdown Voltage | I _D = 250 μA V _{GS} = 0 | 1000 | | | V |
| I _{DSS} | Zero Gate Voltage Drain Current (V _{GS} = 0) | V _{DS} = Max Rating V _{DS} = Max Rating x 0.8 T _c = 125 °C | | | 25 250 | μA μA |
| I _{GSS} | Gate-body Leakage Current (V _{DS} = 0) | V _{GS} = ± 20 V | | | ± 100 | nA |

ON (*)

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------------|-----------------------------------|-----------------------------------------------------------------------------------------|------|------|------|------|
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} = V _{GS} I _D = 250 μA | 2 | 3 | 4 | V |
| R _{DS(on)} | Static Drain-source On Resistance | V _{GS} = 10V I _D = 3 A | | 1.75 | 2 | Ω |
| I _{D(on)} | On State Drain Current | V _{DS} > I _{D(on)} x R _{DS(on)max} V _{GS} = 10 V | 6 | | | A |

DYNAMIC

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------------|------------------------------|------------------------------------------------------------------------------------|------|------|------|------|
| g _{fs} (*) | Forward Transconductance | V _{DS} > I _{D(on)} x R _{DS(on)max} I _D = 3 A | 4 | 5.5 | | S |
| C _{iss} | Input Capacitance | V _{DS} = 25 V f = 1 MHz V _{GS} = 0 | | 2150 | 2800 | pF |
| C _{oss} | Output Capacitance | | | 260 | 330 | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 105 | 130 | pF |

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|-------------------------------|--------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------|------|-----------------|-----------|----------------|
| $t_{d(on)}$ t_r | Turn-on Time Rise Time | $V_{DD} = 500\text{ V}$ $I_D = 3\text{ A}$ $R_G = 50\ \Omega$ $V_{GS} = 10\text{ V}$ (see test circuit, figure 3) | | 70 210 | 90 280 | ns ns |
| $(di/dt)_{on}$ | Turn-on Current Slope | $V_{DD} = 800\text{ V}$ $I_D = 6\text{ A}$ $R_G = 50\ \Omega$ $V_{GS} = 10\text{ V}$ (see test circuit, figure 5) | | 180 | | A/ μ s |
| Q_g Q_{gs} Q_{gd} | Total Gate Charge Gate-Source Charge Gate-Drain Charge | $V_{DD} = 400\text{ V}$ $I_D = 6\text{ A}$ $V_{GS} = 10\text{ V}$ | | 125 15 55 | 150 | nC nC nC |

SWITCHING OFF

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------------------------|-------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------|------|------------------|------------------|----------------|
| $t_{r(Voff)}$ t_f t_c | Off-voltage Rise Time Fall Time Cross-over Time | $V_{DD} = 800\text{ V}$ $I_D = 6\text{ A}$ $R_G = 50\ \Omega$ $V_{GS} = 10\text{ V}$ (see test circuit, figure 5) | | 190 50 265 | 250 65 345 | ns ns ns |

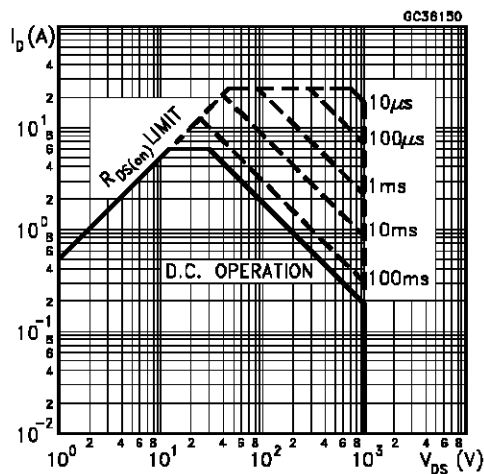
SOURCE DRAIN DIODE

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|-----------------------------------|------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------|------|------------------|---------|--------------------|
| I_{SD} $I_{SDM}(\bullet)$ | Source-drain Current Source-drain Current (pulsed) | | | | 6 24 | A A |
| $V_{SD} (*)$ | Forward On Voltage | $I_{SD} = 6\text{ A}$ $V_{GS} = 0$ | | | 2 | V |
| t_{rr} Q_{rr} I_{RRM} | Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current | $I_{SD} = 6\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 100\text{ V}$ $T_j = 150\text{ }^\circ\text{C}$ (see test circuit, figure 5) | | 1100 31 57 | | ns μ C A |

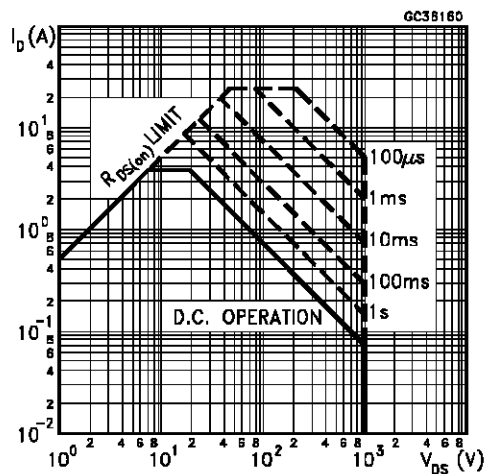
(*) Pulsed: Pulse duration = 300 μ s, duty cycle 1.5%

(\bullet) Pulse width limited by safe operating area

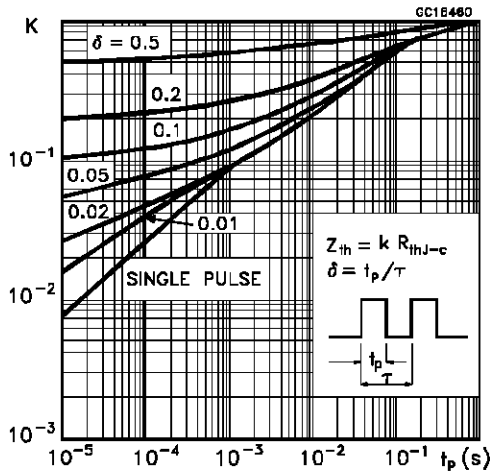
Safe Operating Areas For TO-218



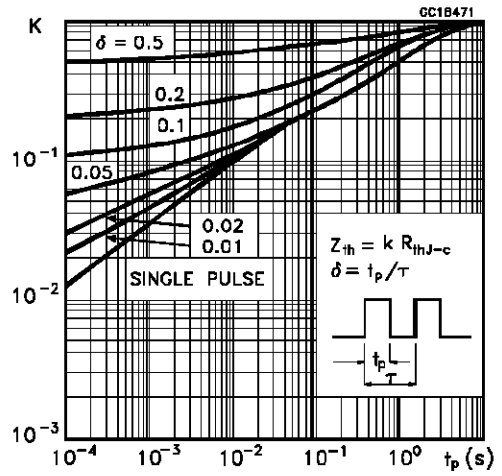
Safe Operating Areas For ISOWATT218



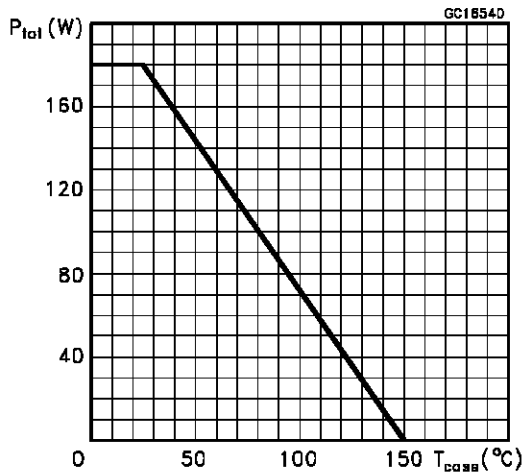
Thermal Impedance For TO-218



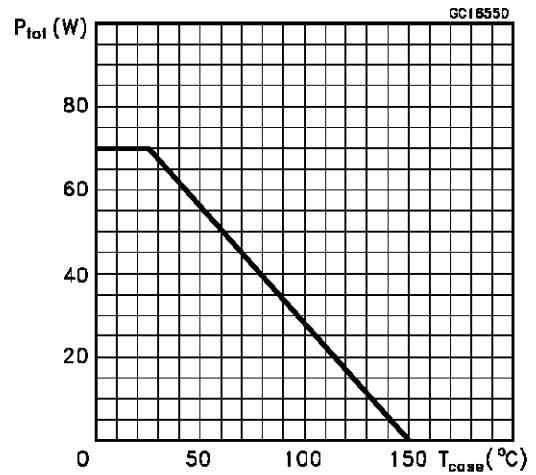
Thermal Impedance For ISOWATT218



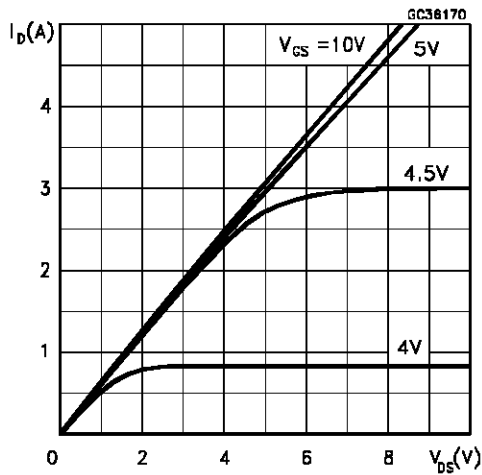
Derating Curve For TO-218



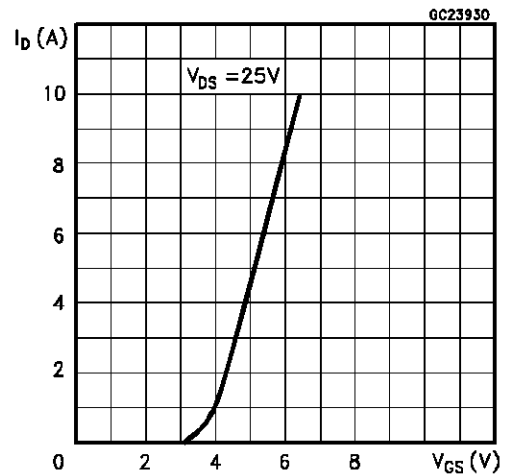
Derating Curve For ISOWATT218



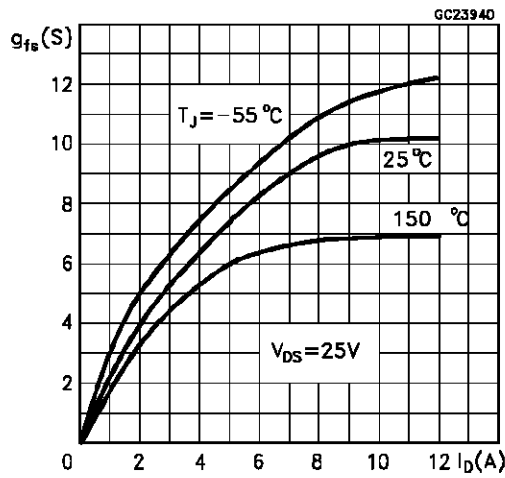
Output Characteristics



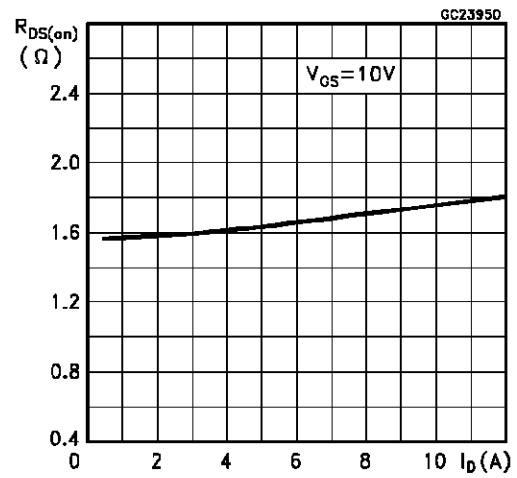
Transfer Characteristics



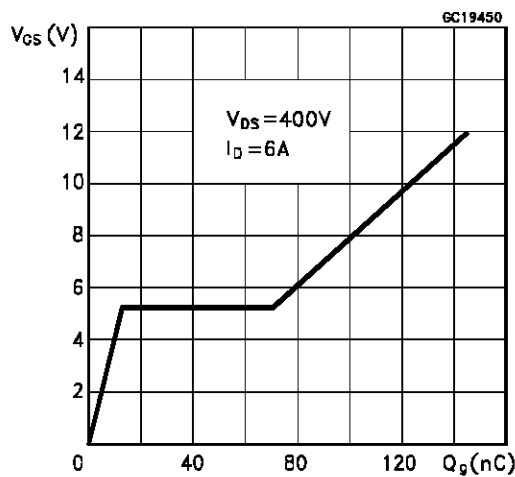
Transconductance



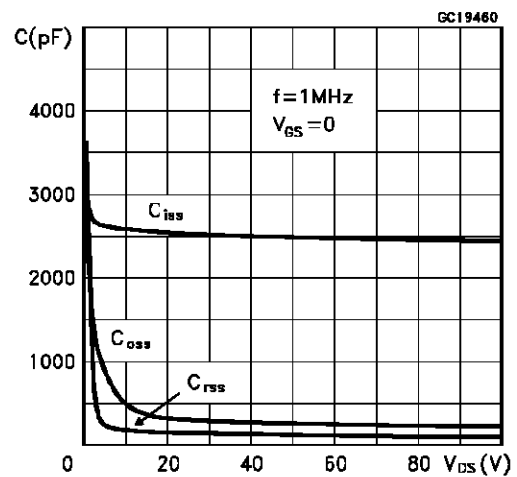
Static Drain-source On Resistance



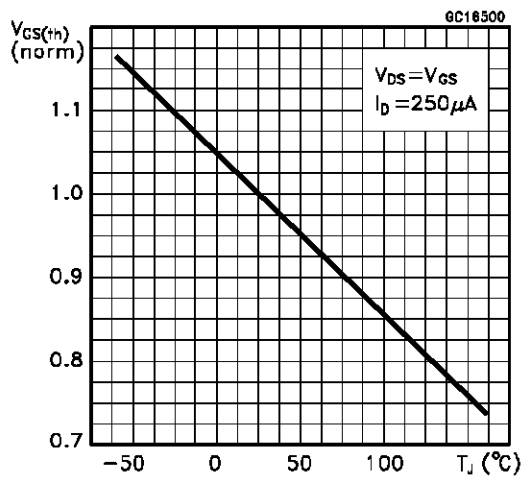
Gate Charge vs Gate-source Voltage



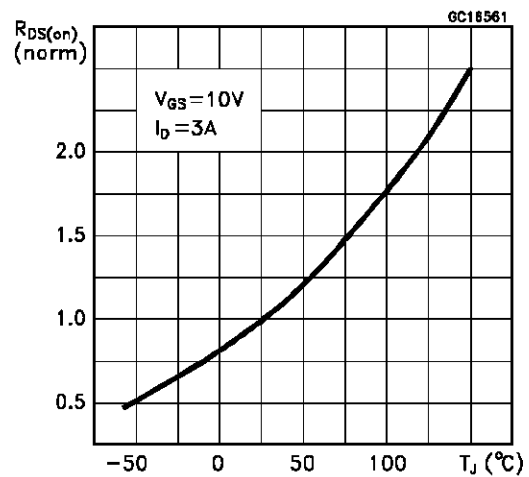
Capacitance Variations



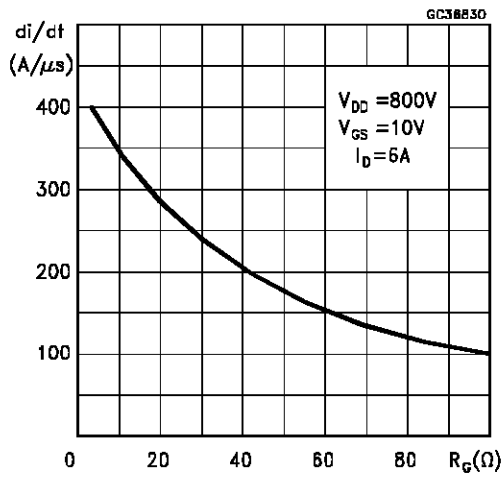
Normalized Gate Threshold Voltage vs Temperature



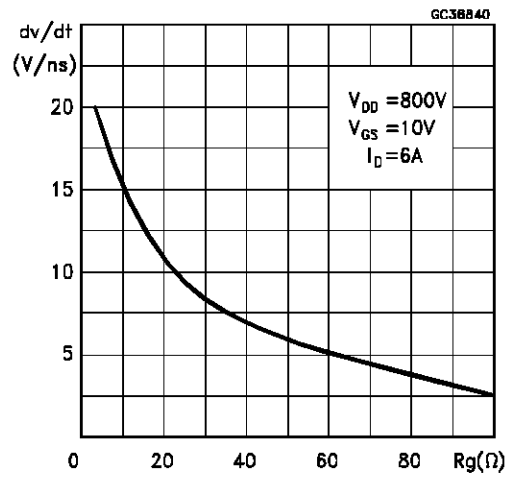
Normalized On Resistance vs Temperature



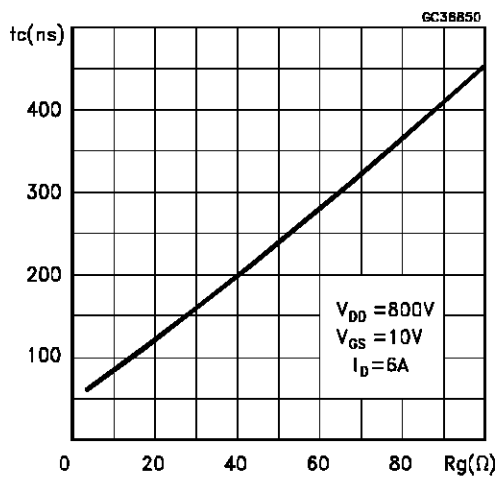
Turn-on Current Slope



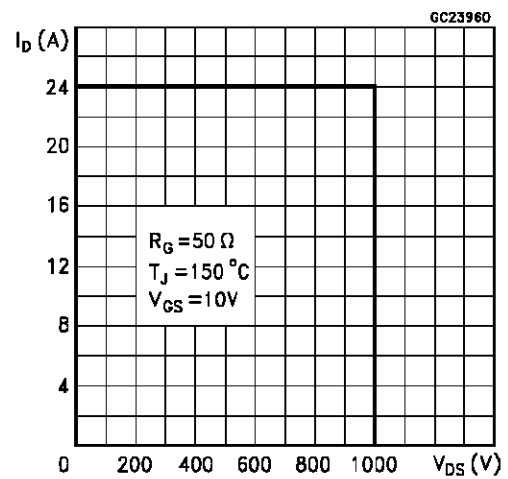
Turn-off Drain-source Voltage Slope



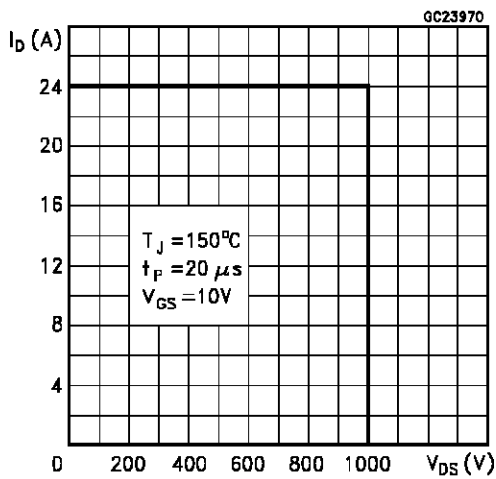
Cross-over Time



Switching Safe Operating Area



Accidental Overload Area



Source-drain Diode Forward Characteristics

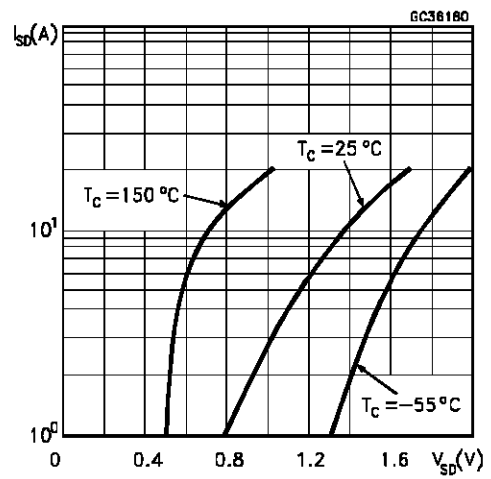


Fig. 1: Unclamped Inductive Load Test Circuits



Fig. 2: Unclamped Inductive Waveforms

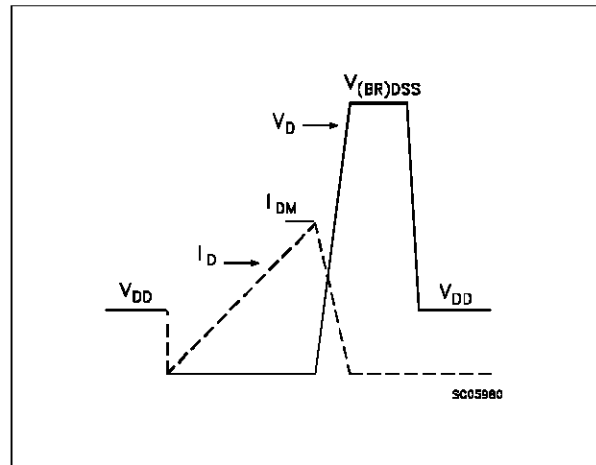


Fig. 3: Switching Times Test Circuits For Resistive Load



Fig. 4: Gate Charge Test Circuit

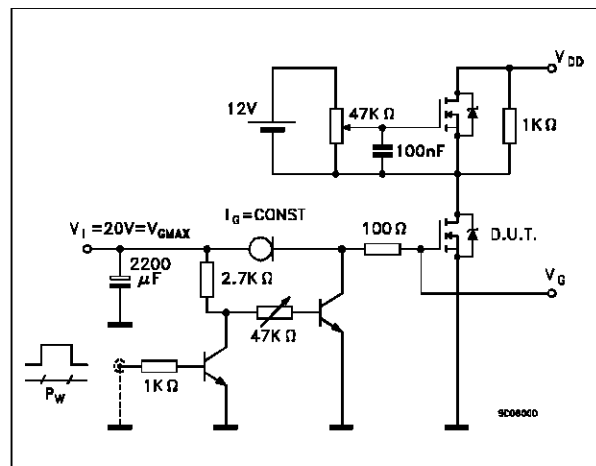
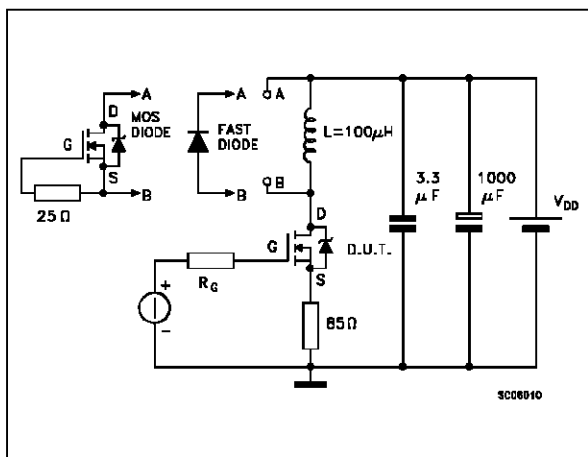
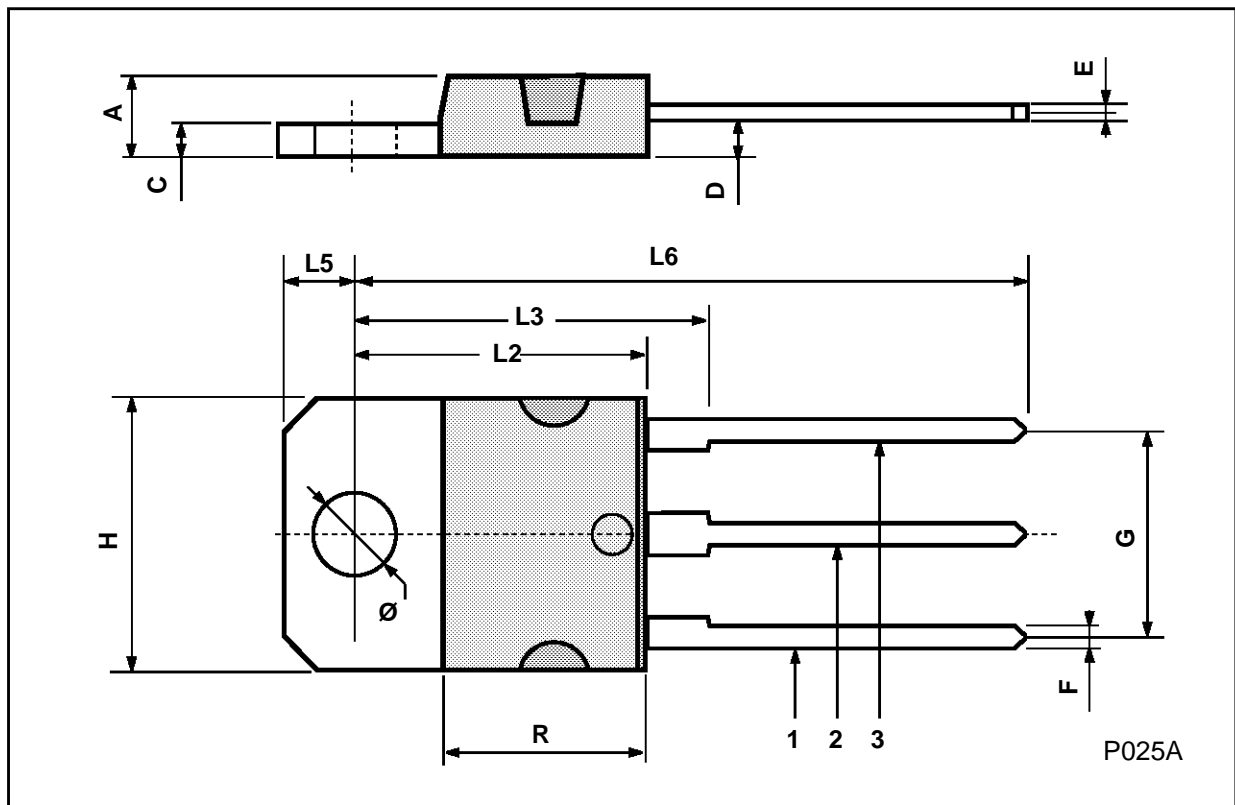


Fig. 5: Test Circuit For Inductive Load Switching And Diode Reverse Recovery Time



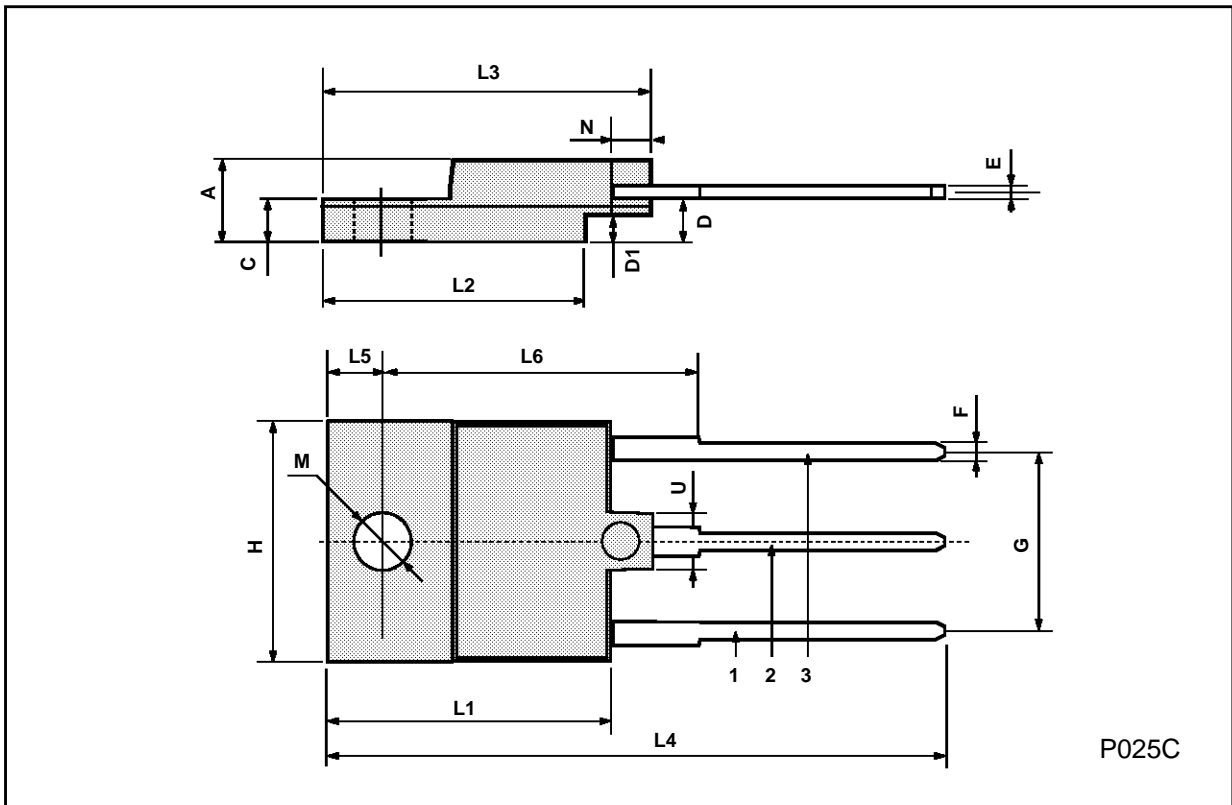
TO-218 (SOT-93) MECHANICAL DATA

| DIM. | mm | | | inch | | |
|------|------|------|------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 4.7 | | 4.9 | 0.185 | | 0.193 |
| C | 1.17 | | 1.37 | 0.046 | | 0.054 |
| D | | 2.5 | | | 0.098 | |
| E | 0.5 | | 0.78 | 0.019 | | 0.030 |
| F | 1.1 | | 1.3 | 0.043 | | 0.051 |
| G | 10.8 | | 11.1 | 0.425 | | 0.437 |
| H | 14.7 | | 15.2 | 0.578 | | 0.598 |
| L2 | - | | 16.2 | - | | 0.637 |
| L3 | | 18 | | | 0.708 | |
| L5 | 3.95 | | 4.15 | 0.155 | | 0.163 |
| L6 | | 31 | | | 1.220 | |
| R | - | | 12.2 | - | | 0.480 |
| Ø | 4 | | 4.1 | 0.157 | | 0.161 |



ISOWATT218 MECHANICAL DATA

| DIM. | mm | | | inch | | |
|------|-------|------|-------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 5.35 | | 5.65 | 0.210 | | 0.222 |
| C | 3.3 | | 3.8 | 0.130 | | 0.149 |
| D | 2.9 | | 3.1 | 0.114 | | 0.122 |
| D1 | 1.88 | | 2.08 | 0.074 | | 0.081 |
| E | 0.45 | | 1 | 0.017 | | 0.039 |
| F | 1.05 | | 1.25 | 0.041 | | 0.049 |
| G | 10.8 | | 11.2 | 0.425 | | 0.441 |
| H | 15.8 | | 16.2 | 0.622 | | 0.637 |
| L1 | 20.8 | | 21.2 | 0.818 | | 0.834 |
| L2 | 19.1 | | 19.9 | 0.752 | | 0.783 |
| L3 | 22.8 | | 23.6 | 0.897 | | 0.929 |
| L4 | 40.5 | | 42.5 | 1.594 | | 1.673 |
| L5 | 4.85 | | 5.25 | 0.190 | | 0.206 |
| L6 | 20.25 | | 20.75 | 0.797 | | 0.817 |
| M | 3.5 | | 3.7 | 0.137 | | 0.145 |
| N | 2.1 | | 2.3 | 0.082 | | 0.090 |
| U | | 4.6 | | | 0.181 | |



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